

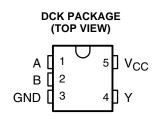
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SINGLE 2-INPUT EXCLUSIVE-OR GATE

Check for Samples: SN74AHCT1G86Q-Q1

FEATURES

- Qualified For Automotive Applications
- Operating Range of 4.5 V to 5.5 V
- Max t_{pd} of 8 ns at 5 V
- Low Power Consumption, 10-μA Max I_{CC}
- ±8-mA Output Drive at 5 V
- Inputs Are TTL-Voltage Compatible



DESCRIPTION

The SN74AHCT1G86 is a single 2-input exclusive-OR gate. The device performs the Boolean function $Y = A \oplus B$ or $Y = \overline{AB} + A\overline{B}$ in positive logic.

ORDERING INFORMATION(1)

T _A	PACK	AGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOT (SC70) - DCK	Reel of 3000	CAHCT1G86QDCKRQ1	B5S

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

FUNCTION TABLE

IN	PUTS	OUTPUT
Α	В	Υ
L	L	L
L	Н	Н
Н	L	Н
Н	Н	L

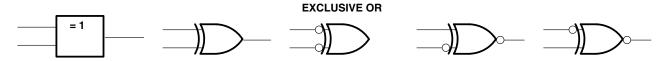


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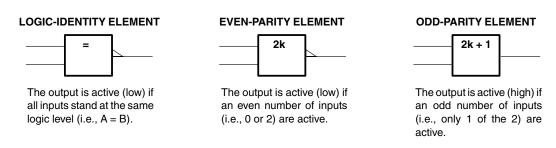
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EXCLUSIVE-OR LOGIC

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



These five equivalent exclusive-OR symbols are valid for an SN74AHCT1G86 gate in positive logic; negation may be shown at any two ports.



ABSOLUTE MAXIMUM RATINGS(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	7	V
VI	Input voltage range ⁽²⁾		-0.5	7	V
Vo	Output voltage range applied in the high- or	low-state (2)	-0.5	$V_{CC} + 0.5$	V
I _{IK}	Input clamp current	V _I < 0 V		-20	V
I _{OK}	Output clamp current	$V_O < 0 \text{ V or } V_O > V_{CC}$		±20	mA
Io	Continuous output current	$V_O = 0 V \text{ to } V_{CC}$		±25	mA
	Continuous current through V _{CC} or GND	,		±50	mA
θ_{JA}	Thermal impedance (3)	DCK package		252	°C/W
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

TRUMENTS

⁽²⁾ The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



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RECOMMENDED OPERATING CONDITIONS(1)

		MIN	MAX	UNIT
V _{CC}	Supply voltage	4.5	5.5	V
V _{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
VI	Input voltage	0	5.5	V
Vo	Output voltage	0	V_{CC}	V
I _{OH}	High-level output current		-8	mA
I _{OL}	Low-level output current		8	mA
Δt/ΔV	Input transition rise or fall rate		20	ns/V
T _A	Operating free-air temperature	-40	125	°C

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

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ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V	Т	MIN	MAX	UNIT		
PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	IVIIIN	IVIAA	UNIT
\/	$I_{OH} = -50 \mu A$	4.5 V	4.4	4.5		4.4		v
V _{OH}	$I_{OH} = -8 \text{ mA}$	4.5 V	3.94			3.8		
V	$I_{OL} = 50 \mu A$	4.5 V			0.1		0.1	V
V _{OL}	I _{OL} = 8 mA	4.5 V			0.36		0.44	
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μА
I _{CC}	$V_I = V_{CC}$ or GND, $I_O = 0$ A	5.5 V			1		10	μΑ
ΔI _{CC} ⁽¹⁾	One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V			1.35		1.5	mA
Cı	$V_I = V_{CC}$ or GND	5 V			10		10	pF

⁽¹⁾ This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC} .

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, V_{CC} = 5 V ±0.5 V, T_A = -40°C to 125°C, see Figure 1

PARAMETER	FROM TO		LOAD	T _A	= 25°C		MIN	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IAIIIA	WAA	UNIT
t _{PLH}	A or D	V	C 50 5 5		5.5	7.9	1	9	20
t _{PHL}	A or B	Y	$C_L = 50 \text{ pF}$		5.5	7.9	1	9	ns

OPERATING CHARACTERISTICS

 $V_{CC} = 5 \text{ V } \pm 0.5 \text{ V}, T_A = -40^{\circ}\text{C to } 125^{\circ}\text{C}$

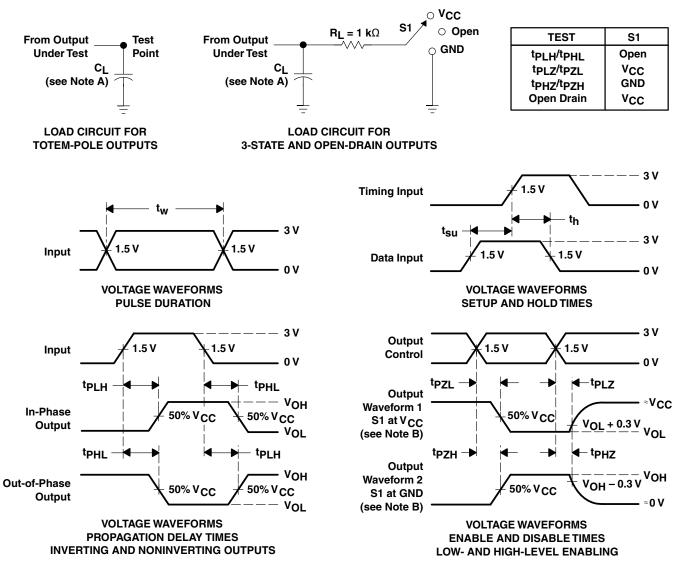
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	No load, f = 1 MHz	18	pF

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PARAMETER MEASUREMENT INFORMATION



- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 - Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 3 ns, $t_f \leq$ 3 ns
- D. The outputs are measured one at a time with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
CAHCT1G86QDCKRQ1	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B5S	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74AHCT1G86-Q1:



PACKAGE OPTION ADDENDUM

10-Dec-2020

• Catalog: SN74AHCT1G86

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Aug-2017

TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
1	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CAHCT1G86QDCKRQ1	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3

www.ti.com 3-Aug-2017



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CAHCT1G86QDCKRQ1	SC70	DCK	5	3000	202.0	201.0	28.0



SMALL OUTLINE TRANSISTOR



NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 This drawing is subject to change without notice.
 Reference JEDEC MO-203.
 Support pin may differ or may not be present.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 7. Board assembly site may have different recommendations for stencil design.



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